

# 2SC3526(H)

Silicon NPN epitaxial planar type

For display video output

## ■ Features

- High transition frequency  $f_T$
- Small collector output capacitance  $C_{ob}$
- Wide current range

## ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

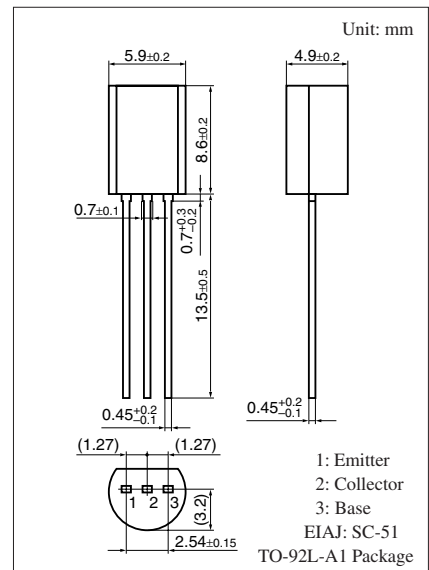
Parameter	Symbol	Rating	Unit
Collector to base voltage	$V_{CBO}$	110	V
Collector to emitter voltage *	$V_{CER}$	100	V
Collector to emitter voltage	$V_{CEO}$	50	V
Emitter to base voltage	$V_{EBO}$	3.5	V
Peak collector current	$I_{CP}$	300	mA
Collector current	$I_C$	150	mA
Collector power dissipation	$P_C$	1.0	W
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

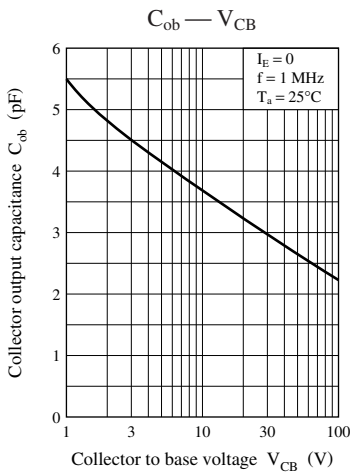
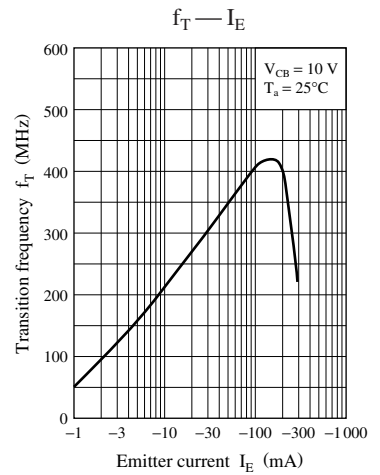
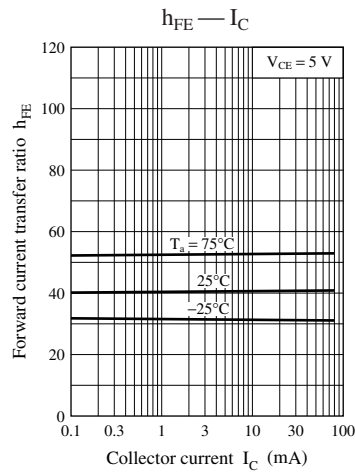
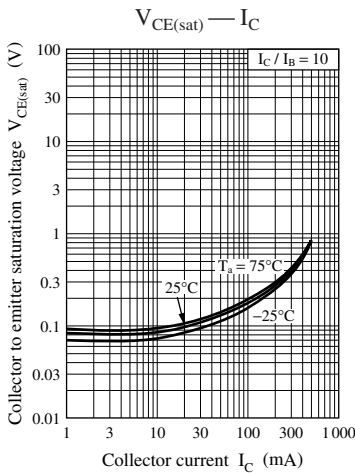
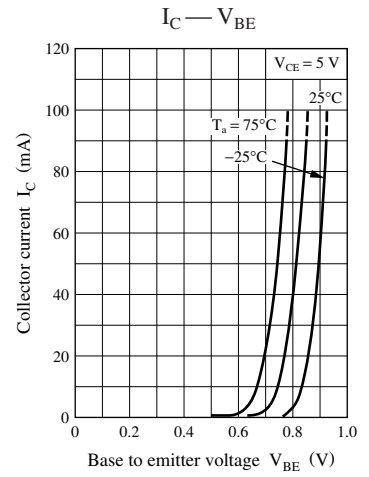
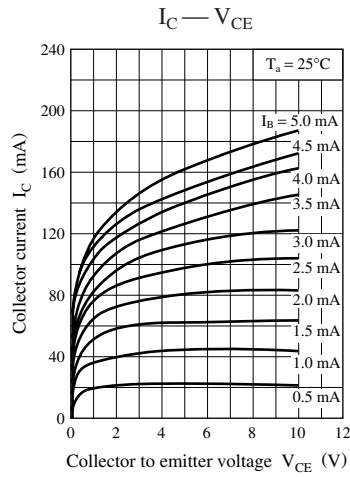
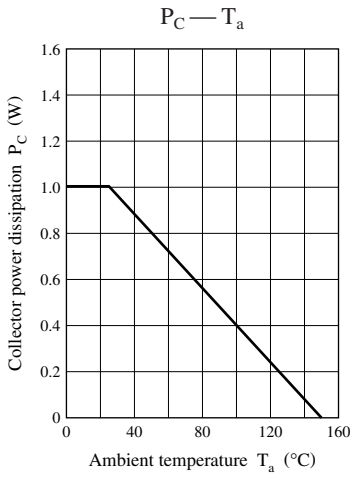
Note) \*:  $R_{EB} = 470 \Omega$

## ■ Electrical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector cutoff current	$I_{CEO}$	$V_{CE} = 35 \text{ V}, I_B = 0$			10	$\mu\text{A}$
Collector to base voltage	$V_{CBO}$	$I_C = 100 \mu\text{A}, I_E = 0$	110			V
Collector to emitter voltage	$V_{CER}$	$I_C = 500 \mu\text{A}, R_{BE} = 470 \Omega$	100			V
Collector to emitter voltage	$V_{CEO}$	$I_C = 1 \text{ mA}, I_B = 0$	50			V
Emitter to base voltage	$V_{EBO}$	$I_E = 100 \mu\text{A}, I_C = 0$	3.5			V
Forward current transfer ratio *	$h_{FE}$	$V_{CE} = 5 \text{ V}, I_C = 100 \text{ mA}$	20			
Collector to emitter saturation voltage *	$V_{CE(sat)}$	$I_C = 150 \text{ mA}, I_B = 15 \text{ mA}$			0.5	V
Transition frequency	$f_{T1}$	$V_{CB} = 10 \text{ V}, I_E = -10 \text{ mA}, f = 200 \text{ MHz}$		300		MHz
	$f_{T2}$	$V_{CB} = 10 \text{ V}, I_E = -110 \text{ mA}, f = 200 \text{ MHz}$		350		
Collector output capacitance	$C_{ob}$	$V_{CB} = 30 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		3		pF

Note) \*: Pulse measurement





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